

# AN1003

## Multilayer Chip Antenna for 2.4GHz & 5~6GHz Wireless Communication



# AN1003 Multilayer Chip Antenna

## ◆ Features

- Light weight and low profile 10.3mm(L)X3.0mm(W)X1.6mm(H)
- Omni-directional in azimuth
- Lead (Pb) Free

## ◆ Applications

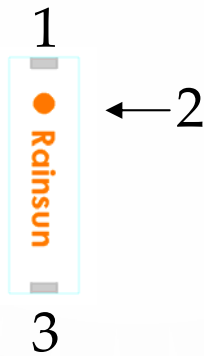
- 2.4GHz & 5~6GHz wireless communications
- 2.4GHz & 5~6GHz Modules
- 802.11a/b/g Wireless LAN System

## Specifications

Center frequency	2.45GHz & 5~6GHz
Peak gain	1dBi
Operation temperature	-40 ~ +85 °C
Storage temperature	-40 ~ +85 °C
VSWR	2.0 (max)
Input Impedance	50 Ohm
Power handling	3W (max)
Bandwidth	2.45GHz 70MHz 5~6GHz 500MHz
Azimuth beamwidth	Omni-directional
Polarization	Linear

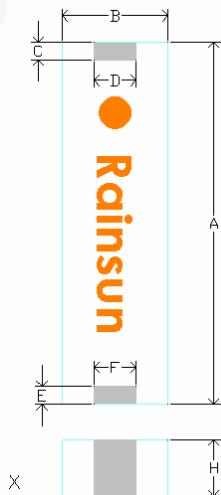
## Pin configuration

Top view



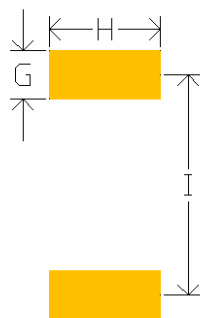
Pin No	Pin assignment
1	Feed termination
2	Feed point mark
3	Solder termination

## Dimensions



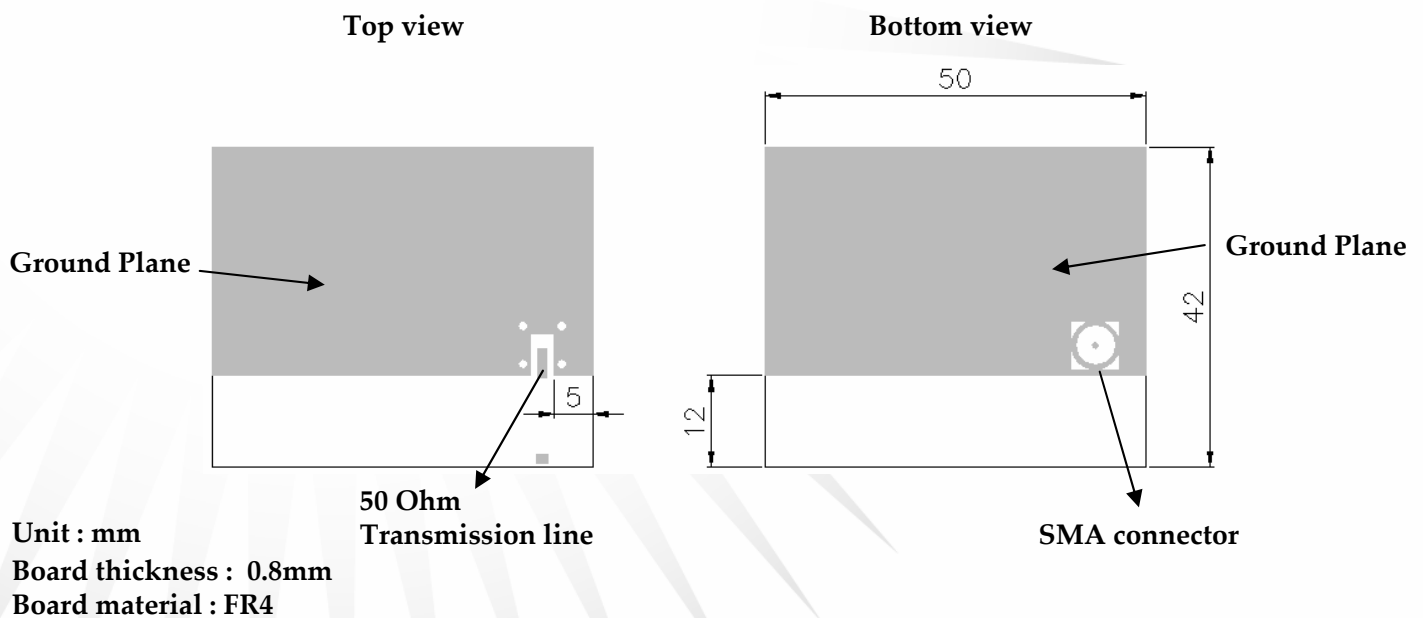
Symbol	Dimensions(mm)
A	$10.3 \pm 0.10$
B	$3.00 \pm 0.10$
C	$0.50 \pm 0.05$
D	$1.50 \pm 0.10$
E	$0.50 \pm 0.05$
F	$1.50 \pm 0.10$
H	$1.60 \pm 0.20$

## PCB Foot Print



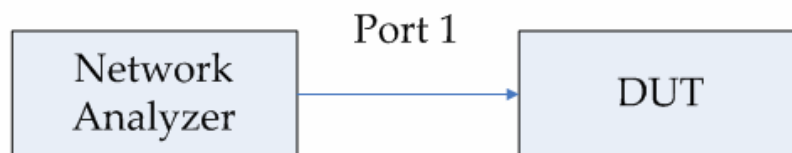
Symbol	Dimensions(mm)
G	1.0
H	1.9
I	10.3

## Recommended Test Board Pattern



**Fig-1**

## Testing Setup



## Measurement



### Testing Instrument:

Anritsu 37369C VNA (Vector Network Analyzer)

VNA calibrate with 1 path reflection only calibration sequence on test board feed point.

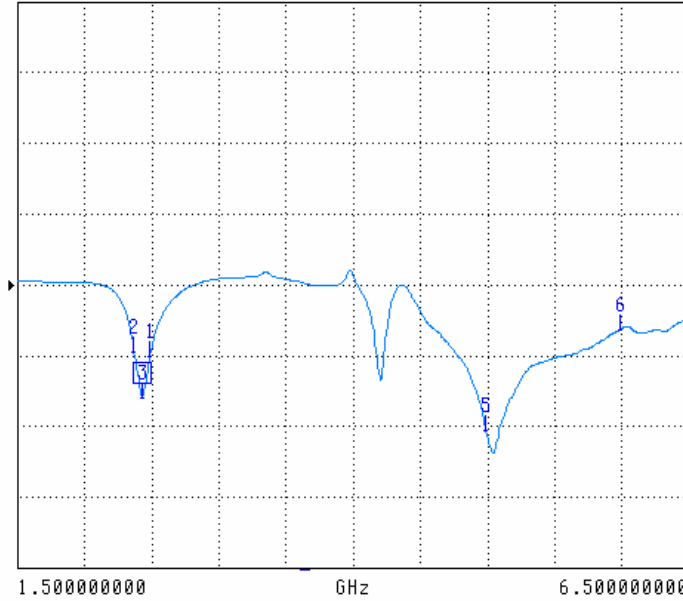
The test board dimension and its layout is the same as Fig-1.

# Typical Electrical Characteristics

## Return loss

S22 REVERSE REFLECTION

LOG MAGNITUDE      REF=0.000 dB      10.000 dB/DIV



CH 4 - S22  
 REFERENCE PLANE  
 0.0000 mm

MARKER 3  
 2.437500000 GHz  
 -15.960 dB

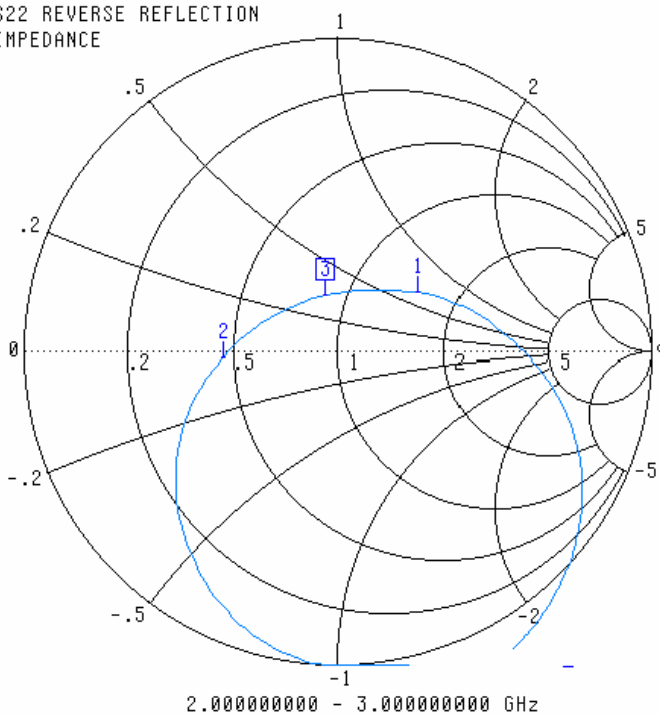
MARKER TO MAX  
 MARKER TO MIN

- 1 2.493750000 GHz  
-10.120 dB
- 2 2.375000000 GHz  
-9.441 dB
- 5 4.993750000 GHz  
-20.719 dB
- 6 5.993750000 GHz  
-6.313 dB

MARKER READOUT  
 FUNCTIONS

## 2.45GHz Smith Chart

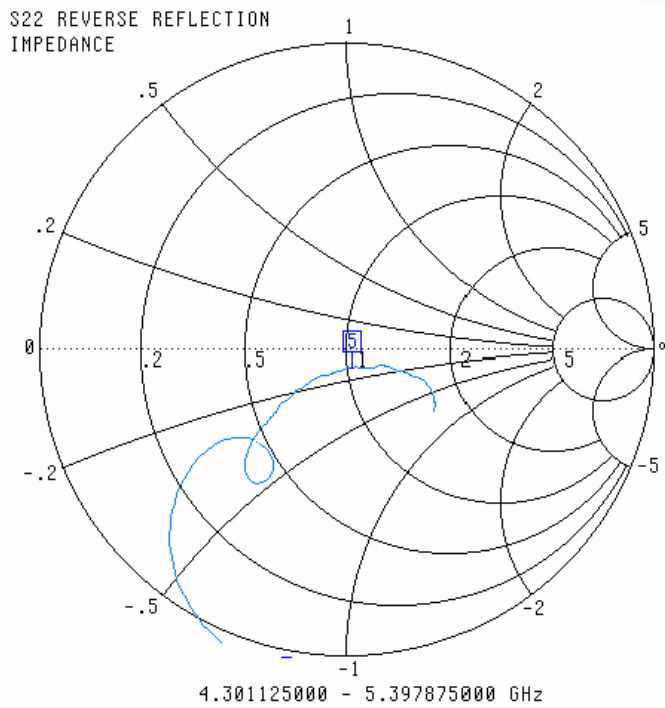
S22 REVERSE REFLECTION  
 IMPEDANCE



**Marker data:**

- 1 : f=2.493 GHz
- 2 : f=2.375 GHz
- 3 : f=2.437 GHz

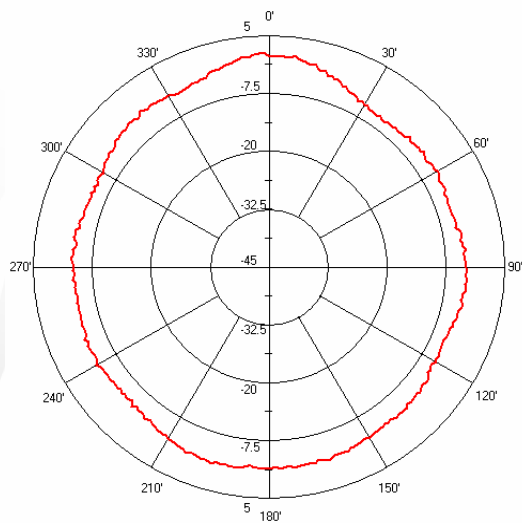
## 5.2GHz Smith Chart



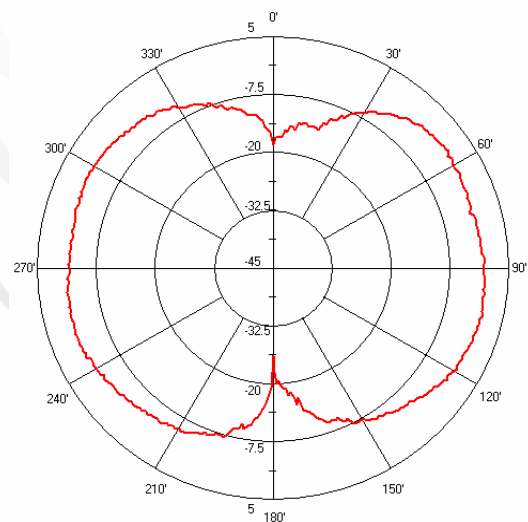
**Marker data:**  
4 : f=4.998 GHz

## Typical Radiation Patterns

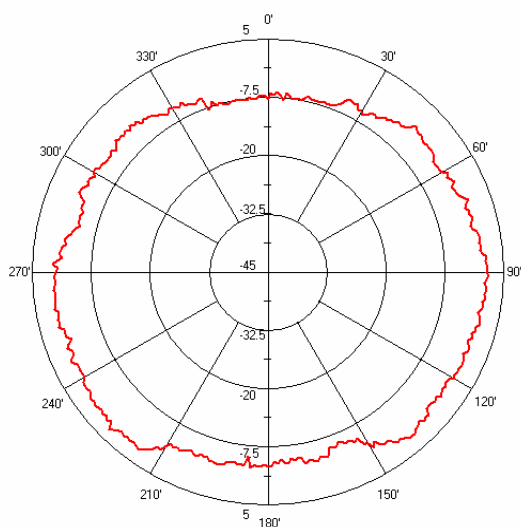
### 2.45 GHz H-Plane



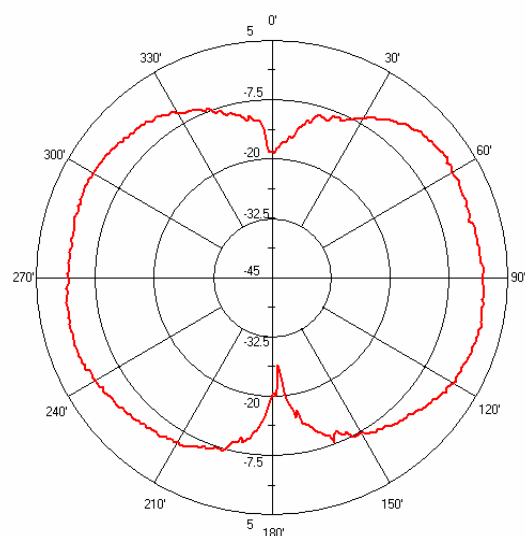
### 2.45 GHz E-Plane



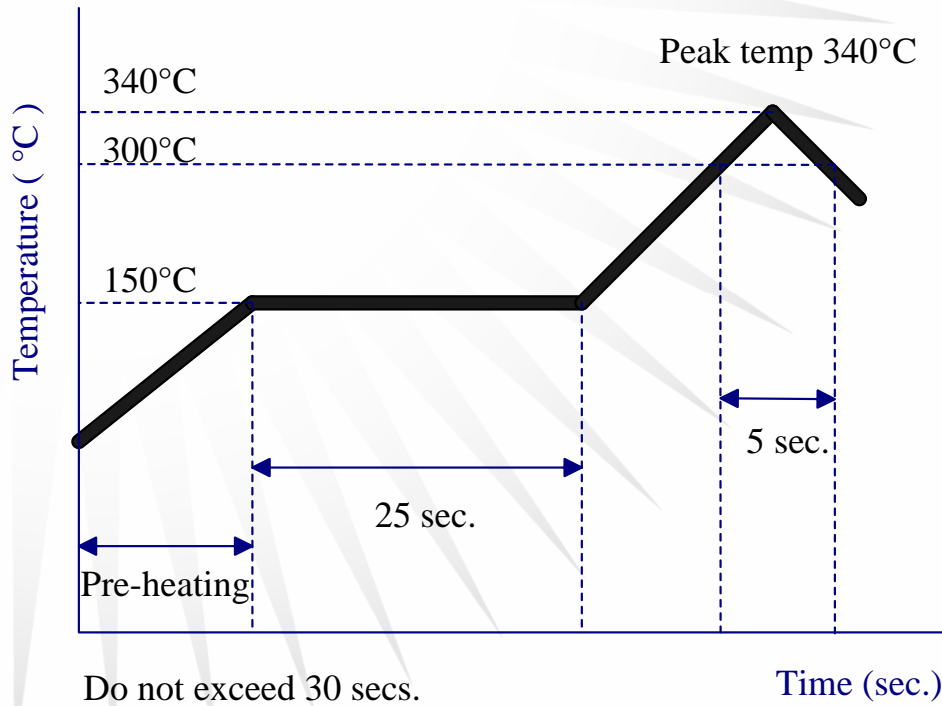
### 5.2 GHz H-Plane



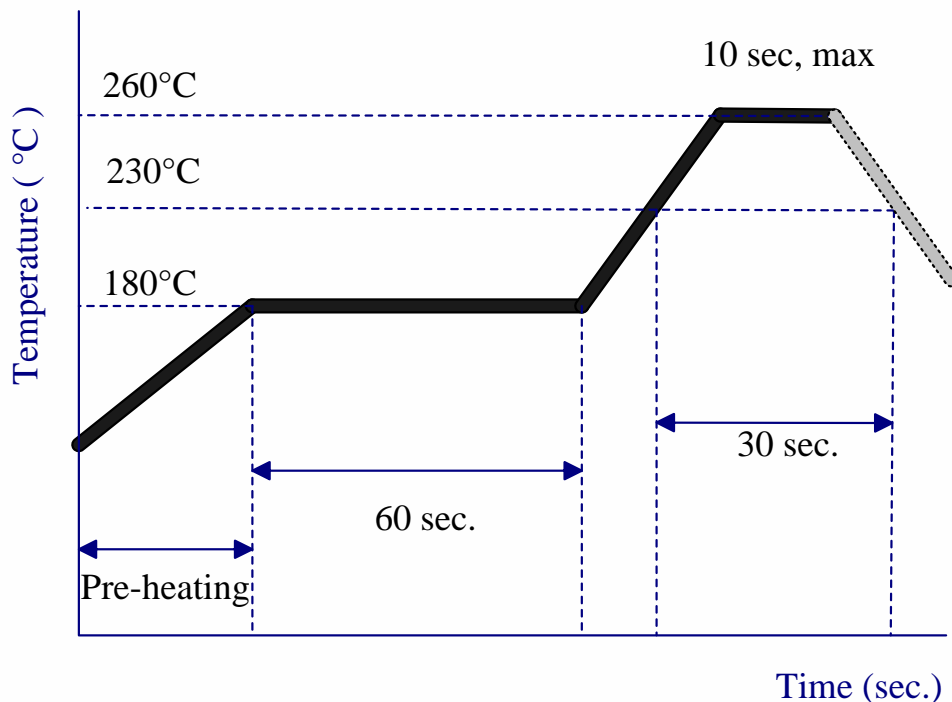
### 5.2 GHz E-Plane



## Typical Soldering Profile for Lead-free Process



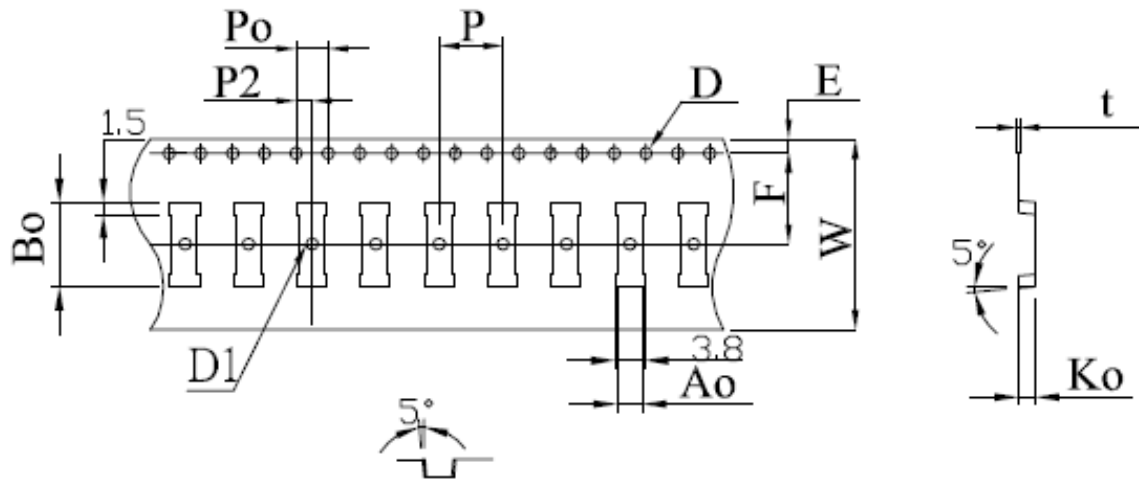
### Reflow Soldering





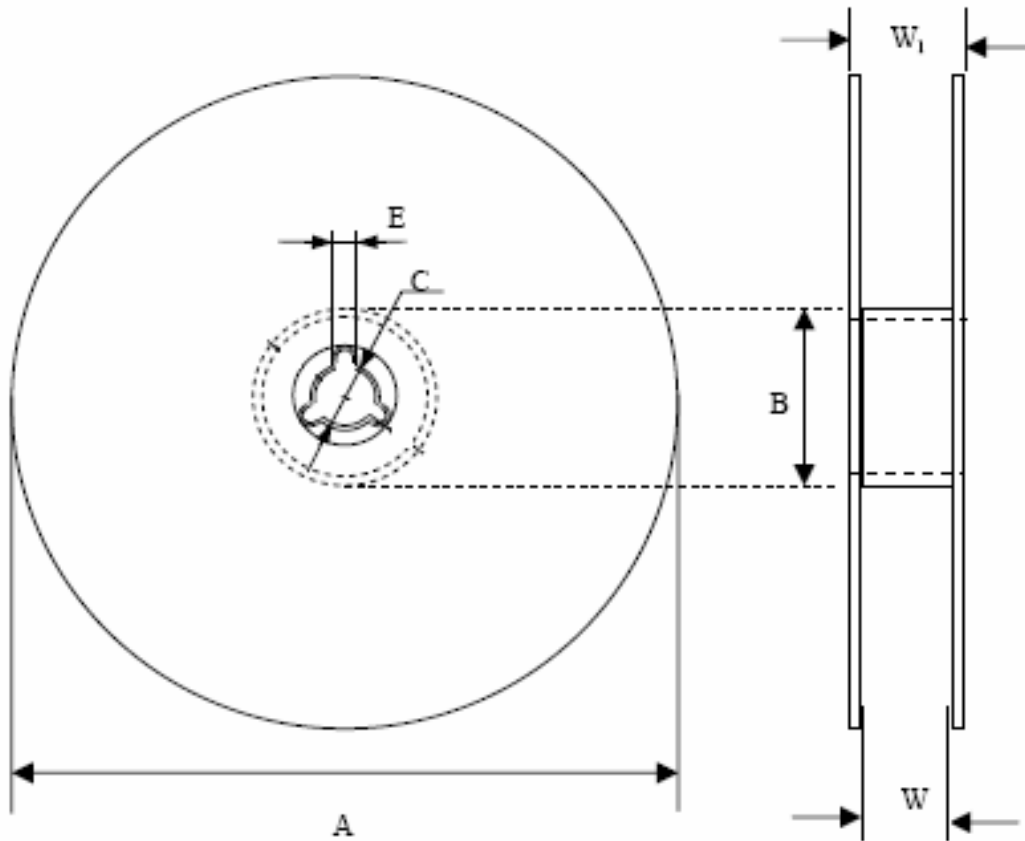
# Packing

## Blister Tape Specifications



Symbol	Dimension	Tolerance	Unit
W	24.00	± 0.30	mm
E	1.75	± 0.10	mm
F	11.50	± 0.10	mm
D	1.50	+ 0.10 - 0.00	mm
D <sub>1</sub>	1.50	+ 0.25 - 0.00	mm
P <sub>0</sub>	4.00	± 0.10	mm
P	8.00	± 0.10	mm
P <sub>2</sub>	2.00	± 0.10	mm
A <sub>0</sub>	3.20	+ 0.10 3.20	mm
B <sub>0</sub>	10.60	± 0.10	mm
K <sub>0</sub>	2.20	± 0.10	mm
t	0.30	± 0.05	mm

# Reel Specifications



Quantity Per Reel	Tape Width (mm)	A (mm)	C (mm)	B (mm)	E (mm)	W (mm)	W <sub>1</sub> (mm)
3,000	24	330±1	13.0±0.5	100.0±0.5	2.2±0.5	24.0±0.5	28.9±0.2